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(54) **POWER ELECTRONICS PACKAGE
LAYOUTS, STRUCTURES, AND/OR
CONFIGURATIONS FOR ONE OR MORE
POWER DEVICES AND PROCESSES
IMPLEMENTING THE SAME**

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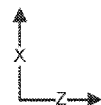
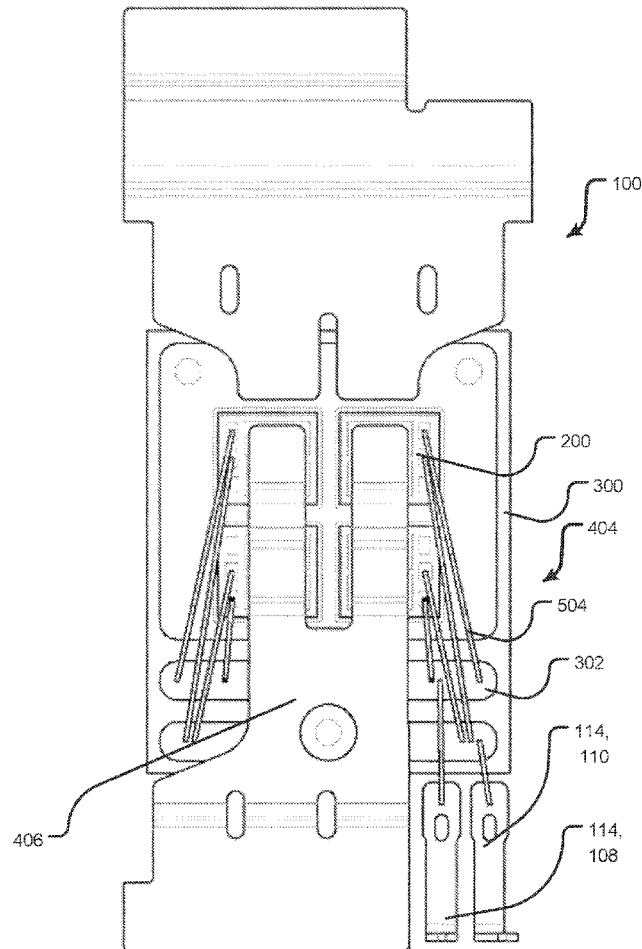
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(57)

ABSTRACT

A power package includes a power substrate; one or more power devices arranged on the power substrate; and a lead frame power interconnection having a lead frame first portion and a lead frame second portion.



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